

1:2 CML Fanout Buffer with Selectable Clock Input

Features

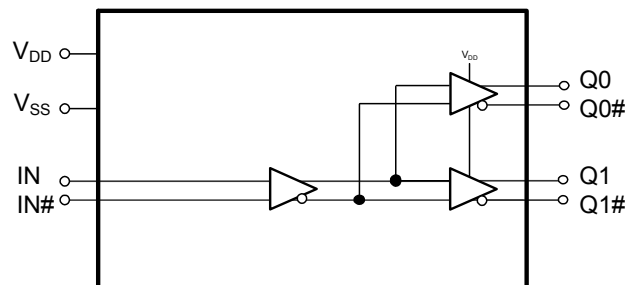
- One current mode logic (CML), High-speed current steering logic (HCSL), or low-voltage positive emitter-coupled logic (LVPECL) input pair distributed to two CML output pairs
- 20-ps maximum output-to-output skew
- 480-ps maximum propagation delay
- 0.15-ps maximum additive RMS phase jitter at 156.25 MHz (12-kHz to 20-MHz offset)
- Up to 1.5 GHz operation
- 8-pin thin shrunk small outline package (TSSOP) package
- 2.5-V or 3.3-V operating voltage ^[1]
- Commercial and industrial operating temperature range

Functional Description

The CY2DM1502 is an ultra-low noise, low-skew, low-propagation delay 1:2 CML, HCSL, or LVPECL to CML fanout buffer targeted to meet the requirements of high-speed clock distribution applications. The device has a fully differential internal architecture that is optimized to achieve low additive jitter and low skew at operating frequencies of up to 1.5 GHz.

For a complete list of related documentation, [click here](#).

Logic Block Diagram



Note

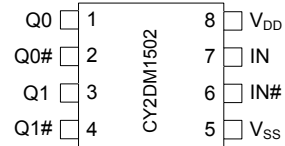
1. Input AC-coupling capacitors are required for voltage-translation applications.

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Pinouts

Figure 1. 8-pin TSSOP Package pinout



Pin Definitions

Pin No.	Pin Name	Pin Type	Description
1, 3	Q(0:1)	Output	CML output clocks
2, 4	Q(0:1)#	Output	CML complementary output clocks
5	V _{SS}	Power	Ground
6	IN#	Input	CML/HCSL/LVPECL complementary input clock
7	IN	Input	CML/HCSL//LVPECL input clock
8	V _{DD}	Power	Power supply

Absolute Maximum Ratings

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	Nonfunctional	-0.5	4.6	V
$V_{IN}^{[2]}$	Input voltage, relative to V_{SS}	Nonfunctional	-0.5	lesser of 4.0 or $V_{DD} + 0.4$	V
$V_{OUT}^{[2]}$	DC output or I/O voltage, relative to V_{SS}	Nonfunctional	-0.5	lesser of 4.0 or $V_{DD} + 0.4$	V
T_S	Storage temperature	Nonfunctional	-55	150	°C
ESD_{HBM}	Electrostatic discharge (ESD) protection (Human body model)	JEDEC STD 22-A114-B	2000	-	V
L_U	Latch up		Meets or exceeds JEDEC Spec JESD78B IC Latch-up Test		
UL-94	Flammability rating	At 1/8 in	V-0		
MSL	Moisture sensitivity level		3		

Operating Conditions

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Supply voltage	2.5-V supply	2.375	2.625	V
		3.3-V supply	3.135	3.465	V
T_A	Ambient operating temperature	Commercial	0	70	°C
		Industrial	-40	85	°C
t_{PU}	Power ramp time	Power-up time for V_{DD} to reach minimum specified voltage (power ramp must be monotonic).	0.05	500	ms

Note

2. The voltage on any I/O pin cannot exceed the power pin during power up. Power supply sequencing is NOT required.

DC Electrical Specifications

($V_{DD} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$; $T_A = 0\text{ }^\circ\text{C}$ to $70\text{ }^\circ\text{C}$ (Commercial) or $-40\text{ }^\circ\text{C}$ to $85\text{ }^\circ\text{C}$ (Industrial))

Parameter	Description	Condition	Min	Max	Unit
I_{DD}	Operating supply current	All CML outputs floating (internal I_{DD})	–	50	mA
V_{IH}	Input high voltage, CML/HCSL/LVPECL inputs IN and IN#		–	$V_{DD} + 0.3$	V
V_{IL}	Input low voltage, CML/HCSL/LVPECL inputs IN and IN#		–0.3	–	V
$V_{ID}^{[3]}$	Input differential amplitude	See Figure 2 on page 7	0.4	1.0	V
V_{ICM}	Input common mode voltage	See Figure 2 on page 7	0.2	$V_{DD} - 0.2$	V
I_{IH}	Input high current, CML/HCSL/LVPECL inputs IN and IN#	Input = $V_{DD}^{[4]}$	–	150	μA
I_{IL}	Input low current, CML/HCSL/LVPECL inputs IN and IN#	Input = $V_{SS}^{[4]}$	–150	–	μA
V_{OH}	CML output high voltage	Terminated with $50\ \Omega$ to $V_{DD}^{[5]}$	$V_{DD} - 0.1$	–	V
V_{OL}	CML output low voltage	Terminated with $50\ \Omega$ to $V_{DD}^{[5]}$	$V_{DD} - 0.7$	$V_{DD} - 0.3$	V
C_{IN}	Input capacitance	Measured at 10 MHz; per pin	–	3	pF

Thermal Resistance

Parameter ^[6]	Description	Test Conditions	8-pin TSSOP	Unit
θ_{JA}	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, in accordance with EIA/JESD51.	162	$^\circ\text{C}/\text{W}$
θ_{JC}	Thermal resistance (junction to case)		29	$^\circ\text{C}/\text{W}$

Notes

- V_{ID} minimum of 400 mV is required to meet all output AC Electrical Specifications. The device is functional with V_{ID} minimum of greater than 200 mV.
- Positive current flows into the input pin, negative current flows out of the input pin.
- Refer to [Figure 3 on page 7](#).
- These parameters are guaranteed by design and are not tested.

AC Electrical Specifications

($V_{DD} = 3.3\text{ V} \pm 5\%$ or $2.5\text{ V} \pm 5\%$; $T_A = 0\text{ }^\circ\text{C}$ to $70\text{ }^\circ\text{C}$ (Commercial) or $-40\text{ }^\circ\text{C}$ to $85\text{ }^\circ\text{C}$ (Industrial))

Parameter	Description	Condition	Min	Typ	Max	Unit
F_{IN}	Input frequency		DC	–	1.5	GHz
F_{OUT}	Output frequency	$F_{OUT} = F_{IN}$	DC	–	1.5	GHz
V_{PP}	CML differential output voltage peak-to-peak, single-ended. Terminated with $50\ \Omega$ to V_{DD} ^[5]	$F_{out} = \text{DC to } 150\text{ MHz}$	250	–	700	mV
		$F_{out} = >150\text{ MHz to } 1.5\text{ GHz}$	250	–	600	mV
t_{PD} ^[7]	Propagation delay input pair to output pair	Input rise/fall time < 1.5 ns (20% to 80%)	–	–	480	ps
t_{ODC} ^[8]	Output duty cycle	50% duty cycle at input Frequency range up to 1 GHz	48	–	52	%
t_{SK1} ^[9]	Output-to-output skew	Any output to any output, with same load conditions at DUT	–	–	20	ps
t_{SK1D} ^[9]	Device-to-device output skew	Any output to any output between two or more devices. Devices must have the same input and have the same output load.	–	–	150	ps
PN_{ADD}	Additive RMS phase noise 156.25-MHz Input Rise/fall time < 150 ps (20% to 80%) $V_{ID} > 400\text{ mV}$	Offset = 1 kHz	–	–	–120	dBc/Hz
		Offset = 10 kHz	–	–	–130	dBc/Hz
		Offset = 100 kHz	–	–	–135	dBc/Hz
		Offset = 1 MHz	–	–	–145	dBc/Hz
		Offset = 10 MHz	–	–	–153	dBc/Hz
		Offset = 20 MHz	–	–	–155	dBc/Hz
t_{JIT} ^[10]	Additive RMS phase jitter (Random)	156.25 MHz, 12 kHz to 20 MHz offset; input rise/fall time < 150 ps (20% to 80%), $V_{ID} > 400\text{ mV}$	–	–	0.15	ps
t_R, t_F ^[11]	Output rise/fall time	50% duty cycle at input, 20% to 80% of full swing (V_{OL} to V_{OH}) Input rise/fall time < 1.5 ns (20% to 80%) Measured at 1 GHz	–	–	250	ps

Notes

7. Refer to [Figure 4 on page 7](#).
8. Refer to [Figure 5 on page 7](#).
9. Refer to [Figure 6 on page 8](#).
10. Refer to [Figure 7 on page 8](#).
11. Refer to [Figure 8 on page 8](#).

Figure 2. Input Differential and Common Mode Voltages

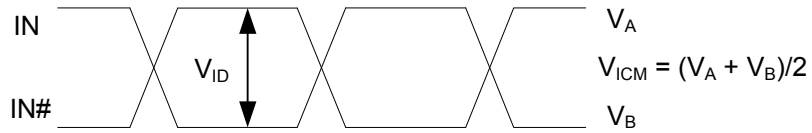


Figure 3. Output Differential Voltage

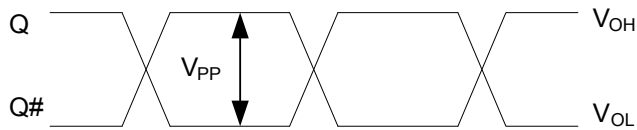


Figure 4. Input to Any Output Pair Propagation Delay

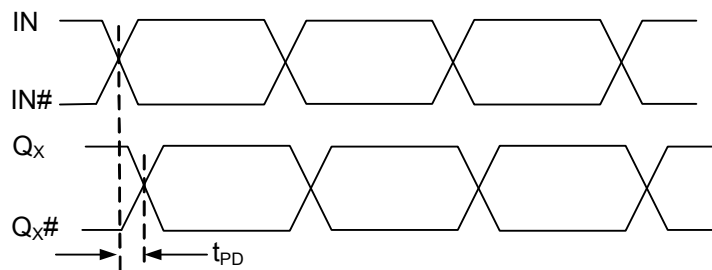


Figure 5. Output Duty Cycle

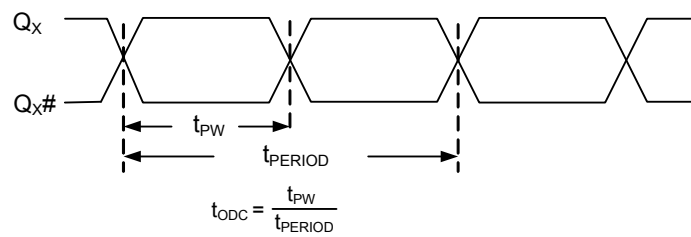


Figure 6. Output-to-Output and Device-to-Device Skew

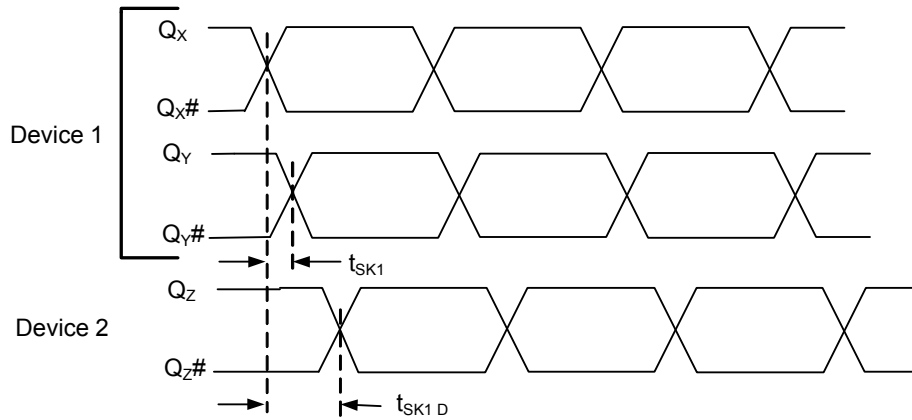


Figure 7. RMS Phase Jitter

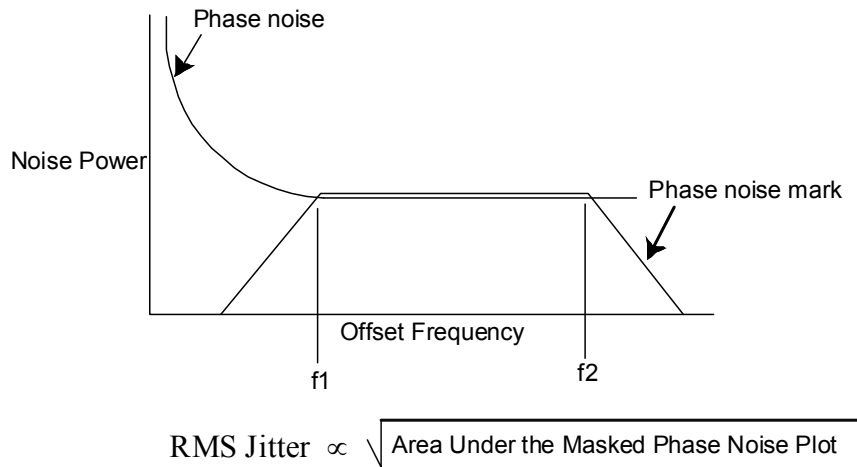
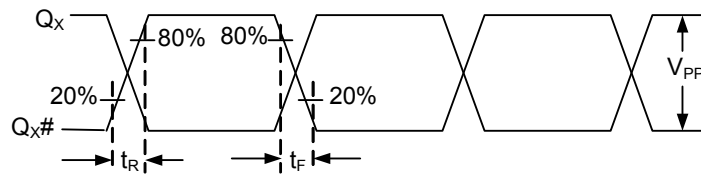


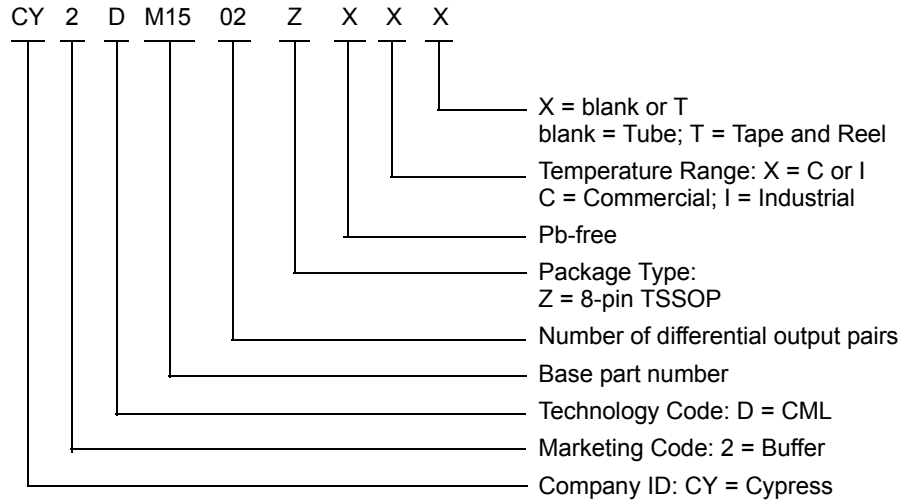
Figure 8. Output Rise/Fall Time



Ordering Information

Part Number	Type	Production Flow
Pb-free		
CY2DM1502ZXI	8-pin TSSOP	Industrial, -40 °C to 85 °C
CY2DM1502ZXIT	8-pin TSSOP tape and reel	Industrial, -40 °C to 85 °C

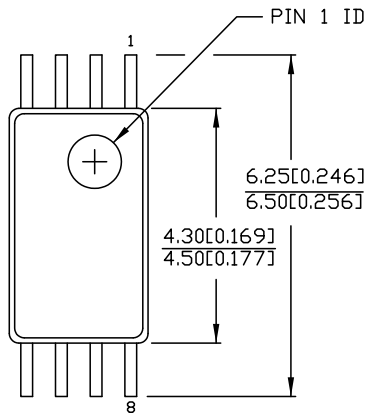
Ordering Code Definitions



Package Diagram

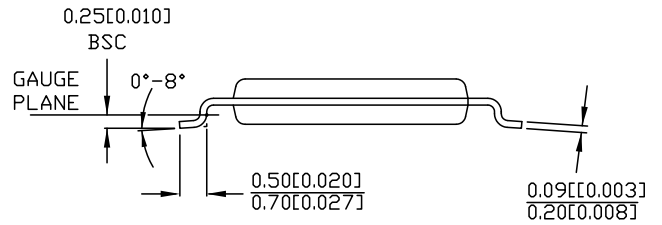
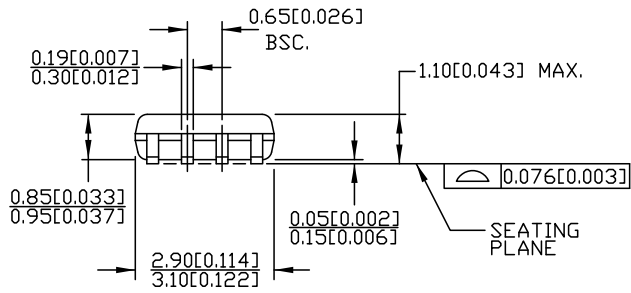
Figure 9. 8-pin TSSOP (4.40 MM Body) Z08.173/ZZ08.173 Package Outline, 51-85093

8 Lead TSSOP 4.40 MM BODY



DIMENSIONS IN MM[INCHES] MIN.
MAX.
REFERENCE JEDEC MO-153

PART #	
Z08.173	STANDARD PKG.
ZZ08.173	LEAD FREE PKG.



51-85093 *E

Acronyms

Table 1. Acronyms Used in this Document

Acronym	Description
CML	current mode logic
ESD	electrostatic discharge
HBM	human body model
HCSL	high-speed current steering logic
JEDEC	joint electron devices engineering council
LVDS	low-voltage differential signal
LVC MOS	low-voltage complementary metal oxide semiconductor
LVPECL	low-voltage positive emitter-coupled logic
RMS	root mean square
TSSOP	thin shrunk small outline package

Document Conventions

Units of Measure

Table 2. Units of Measure

Symbol	Unit of Measure
°C	degree Celsius
dBc	decibels relative to the carrier
GHz	gigahertz
Hz	hertz
kΩ	kilohm
μA	microampere
μF	microfarad
μs	microsecond
mA	milliampere
ms	millisecond
mV	millivolt
MHz	megahertz
ns	nanosecond
Ω	ohm
pF	picofarad
ps	picosecond
V	volt
W	watt

Document History Page

Document Title: CY2DM1502, 1:2 CML Fanout Buffer with Selectable Clock Input				
Document Number: 001-56315				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	2782891	CXQ	10/09/09	New Datasheet.
*A	2838916	CXQ	01/05/2010	<p>Changed status from "ADVANCE" to "PRELIMINARY".</p> <p>Changed from 0.34 ps to 0.25 ps maximum additive jitter in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table on page 4.</p> <p>Added t_{PU} spec to the Operating Conditions table on page 2.</p> <p>Removed V_{OH} spec maximum of V_{DD} in the DC Electrical Specs table on page 3.</p> <p>Changed V_{OL} spec min from $V_{DD} - 0.6V$ to $V_{DD} - 0.7V$; changed max from $V_{DD} - 0.4V$ to $V_{DD} - 0.3V$ in the DC Electrical Specs table on page 3.</p> <p>Removed V_{OD} spec of minimum 300 mV, maximum 450 mV in the DC Electrical Specs table on page 3.</p> <p>Added R_P spec in the DC Electrical Specs table on page 3. Min = 60 kΩ, Max = 140 kΩ.</p> <p>Added a measurement definition for C_{IN} in the DC Electrical Specs table on page 3.</p> <p>Added V_{PP} spec to the AC Electrical Specs table on page 4. V_{PP} max = 700 mV for DC - 150 MHz and max = 600 mV for 150 MHz to 1.5 GHz. V_{PP} min = 250 mV over the entire range.</p> <p>Changed letter case and some names of all the timing parameters in the AC Electrical Specs table on page 4 to be consistent with EROS.</p> <p>Lowered all additive phase noise mask specs by 3 dB in in the AC Electrical Specs table on page 4.</p> <p>Added condition to t_R and t_F specs in the AC Electrical specs table on page 4 that input rise/fall time must be less than 1.5 ns (20% to 80%).</p> <p>Changed letter case and some names of all the timing parameters in Figures 3, 4, 5, 6 and 8, to be consistent with EROS.</p>
*B	3011766	CXQ	08/20/2010	<p>Changed from 0.25 ps to 0.11 ps maximum additive jitter in "Features" on page 1 and in t_{JIT} in the AC Electrical Specs table.</p> <p>Added note 3 to describe I_{IH} and I_{IL} specs.</p> <p>Removed reference to data distribution from "Functional Description".</p> <p>Changed R_P for diff inputs from 100 kΩ to 150 kΩ in the Logic Block Diagram and from 60 kΩ min / 140 kΩ max to 90 kΩ min / 210 kΩ max in the DC Electrical Specs table.</p> <p>Added max V_{ID} of 1.0V in DC Electrical Specs table.</p> <p>Updated phase noise specs for 1 k/10 k/100 k/1 M/10 M/20 MHz offset to -120/-130/-135/-150/-150/-150dBc/Hz, respectively, in the AC Electrical Specs table.</p> <p>Added "Frequency range up to 1 GHz" condition to t_{ODC} spec.</p> <p>Updated package diagram.</p> <p>Added Acronyms and Ordering Code Definition.</p>
*C	3017258	CXQ	08/27/2010	Corrected Output Rise/Fall time diagram.
*D	3100234	CXQ	11/18/2010	<p>Updated Phase jitter to 0.15ps max from 0.11ps max.</p> <p>Changed V_{IN} and V_{OUT} specs from 4.0V to "lesser of 4.0 or $V_{DD} + 0.4$"</p> <p>Removed 200mA min LU spec, replaced with "Meets or exceeds JEDEC Spec JESD78B IC Latchup Test"</p> <p>Removed R_P spec for differential input clock pins IN_x and $IN_x\#$.</p> <p>Changed C_{IN} condition to "Measured at 10 MHz".</p> <p>Changed PN_{ADD} specs for 1MHz, 10MHz, and 20MHz offsets.</p> <p>Added condition "Measured at 1 GHz" to t_R, t_F specs.</p>
*E	3137726	CXQ	01/13/2011	<p>Removed "Preliminary" status heading.</p> <p>Removed resistors from $IN/IN\#$ in Logic Block Diagram.</p>
*F	3090938	CXQ	02/25/2011	Post to external web.

Document History Page (continued)

Document Title: CY2DM1502, 1:2 CML Fanout Buffer with Selectable Clock Input Document Number: 001-56315				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
*G	3410372	PURU	10/18/2011	Adding HCSL to Features , Functional Description , Pin Definitions , and DC Electrical Specifications sections. The min value of V_{ICM} is changed from 0.5 to 0.2 in DC Electrical Specifications .
*H	3878396	PURU	01/21/2013	Updated to new template.
*I	4587249	PURU	12/04/2014	Updated Functional Description : Added "For a complete list of related documentation, click here ." at the end. Updated Ordering Information : Removed the prune part numbers CY2DM1502ZXC and CY2DM1502ZXCT. Updated Package Diagram : spec 51-85093 – Changed revision from *D to *E.
*J	5272915	PSR	05/16/2016	Added Thermal Resistance . Updated to new template.
*K	5966682	AESATMP8	11/14/2017	Updated logo and Copyright.

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